ABSTRACT

The present invention provides for a semiconductor device that facilitates optical recognition to prevent poor wire bonding from occurring. The semiconductor device associated with the present invention comprises a semiconductor chip (20) having a plurality of electrodes and a lead (16) comprising an inner lead portion (16a) connected to each of the electrodes with a wire (24) and an outer lead portion (16b) providing an external terminal. The inner lead portion (16a) is formed with a groove (18) providing a center index portion at a center along its width in a bonding area of the wire (24).